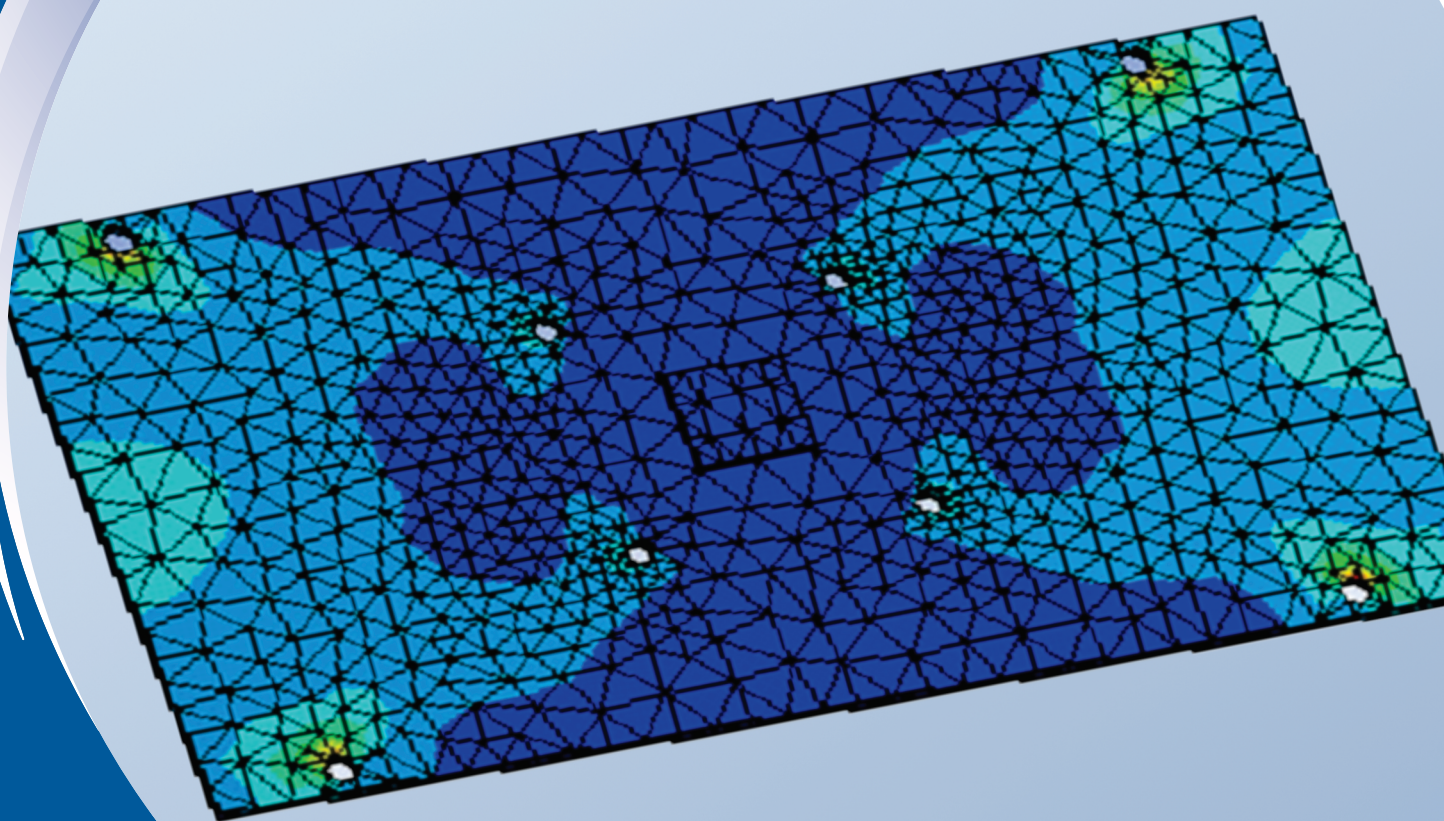


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Editorial / Uvodnik

Respected readers,

Over the last years, our journal operations and processes ran smoothly and I am grateful to the Editorial Board members, reviewers and technical support team for their valuable contribution to the continuous operations, effectiveness and success.

Since 2019 all published papers are open-access (under CC-BY Creative Commons Attribution 4.0 License) and available in WoS, Scopus, DOAJ or on the journal web pages by a single mouse click. I sincerely hope that open-access policy helps us in wider dissemination and larger readership.

In 2025 we received more than 220 manuscripts, out of which only 21 have been accepted for publication so far, while 105 were out of scope and more than 150 manuscripts were rejected. The success rate remains low (below 10% in 2025) primarily because we receive many manuscripts are out-of-scope or do not meet the quality and scientific originality that we aim at. Citation metrics for 2024 (released in June 2025) is sound and improving:

- JCR IF-2023= 0.8
- SNIP-2023=0.433
- CiteScore-2023=1.9

which according to SCOPUS ranking positions us at 39th percentile (3rd quarter, Q3) of the journals in the field of *Electrical and Electronic Engineering* (585th place out of 970 journals) and at 30th percentile (3rd quarter, Q3) of the journals in the field of *Materials Science – Electronic, Optical and Magnetic Materials* (213th place out of 305 journals).

In 2025 we published 21 original scientific papers. Here is the link to access them directly: <https://www.midem-drustvo.si/Journal/Issues.aspx>. I selected few highlights from papers published in 2025.

In the first issue (1/2025) the original scientific paper with strong elements of a review paper entitled "*Challenges for Large-Scale Deployment of WBG in Power Electronics*" [1] covers wide bandgap (WBG) semiconductors as a promising solution in power electronics due to their superior characteristics and brings critical assessment material properties as well as packaging techniques to be further exploited.

In the second issue (2/2025) the original scientific paper "*Dual Band Reflectarray for Transmitter/Receiver Ground Station Drone Tracking Applications*" [2] brings novel design of a dual-band, single-layer reflect array offering high gain for dual-polarized drone ground station tracking applications with minimized design complexity using a low profile antenna with a simple structure and reduced weight.

In the third issue (3/2025) the original scientific paper "*An Air-gapped Cavity Filter Based on MEMS Process for 5G Millimeter Wave Applications*" [3] covers design, fabrication and characterization of 24.25-27.5 GHz bandpass filter using air-gapped structure fabricated through high-precision Micro Electro-Mechanical System process.

In the last issue (4/2025) the original scientific paper "*A Wireless Optical Gate and IMU System for Agility Assessment: Architecture, Synchronization and Validation*" [4] sheds light on advanced sensing nodes and a modular measurement system that fuses infrared (IR) optical gates for robust event detection with a trunk-worn inertial measurement unit (IMU) for kinematic profiling as a case application in sports.

We strive and look forward to serving you as a part of your success in science, technology and engineering and look forward to receiving your future manuscript(s) on our submission page (<http://ojs.midem-drustvo.si/>).

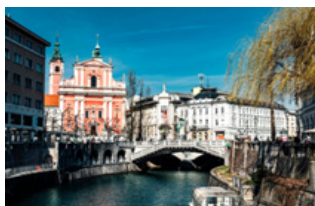
Take care, keep your focus and stay resilient to global volatility, uncertainty and insecurity!

Prof. Marko Topič
Editor-in-Chief

5 March 2026

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Call for Papers
MIDEM 2026

*61th INTERNATIONAL CONFERENCE ON MICROELECTRONICS, DEVICES AND MATERIALS
WITH THE WORKSHOP ON INTEGRATED PHOTONICS*

September 28st – 30th, 2026

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DEADLINES:

Abstract submission:
May 15, 2026

Acceptance notification:
June 30, 2026

Full paper submission:
September 1, 2026

Accepted papers will be published
in the Conference Proceedings.

Further information and updates:
<http://www.midem-drustvo.si/>

TOPICS OF INTEREST include but are not limited to:

- Integrated photonic circuits, devices and systems (WS),
- Chips and semiconductor technologies,
- Sensors and actuators,
- Electromechanical devices and micro/nanosystems,
- Electronics, electromagnetic compatibility,
- Nanoelectronics, quantum chips and devices,
- Optoelectronics and photonics,
- Photovoltaic materials, devices and systems,
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